

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT4448336

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TSUTOMU KAWAMURA	05/09/2017
KAORU KAWABATA	05/15/2017
RYOUSUKE NAKAMURA	04/25/2017
HIROSHIGE KIKUCHI	05/09/2017
SUSUMU IKEDA	05/10/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HITACHI, LTD.
<b>Street Address:</b>	6-6, MARUNOUCHI 1-CHOME
<b>Internal Address:</b>	CHIYODA-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	100-8280
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15533675
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	215-568-6400
<b>Email:</b>	lgivigliano@vklaw.com
<b>Correspondent Name:</b>	VOLPE AND KOENIG, P.C.
<b>Address Line 1:</b>	UNITED PLAZA
<b>Address Line 2:</b>	30 SOUTH 17TH STREET, 18TH FLOOR
<b>Address Line 4:</b>	PHILADELPHIA, PENNSYLVANIA 19103
<b>ATTORNEY DOCKET NUMBER:</b>	HITACHI2-111401268US01
<b>NAME OF SUBMITTER:</b>	DANIEL N. CALDER
<b>SIGNATURE:</b>	/Daniel N. Calder/
<b>DATE SIGNED:</b>	06/07/2017

**Total Attachments: 5**

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# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280 Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

Heat source system managing device, heat source system managing method, and program

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd. its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Tsutomu Kawamura</u> Tsutomu KAWAMURA	<u>5/9 / 2017</u>
2) _____ Kaoru KAWABATA	_____
3) _____ Ryoustake NAKAMURA	_____
4) _____ Hiroshige KIKUCHI	_____
5) _____ Susumu IKEDA	_____
6) _____	_____
7) _____	_____
8) _____	_____

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1)	Tsutomu KAWAMURA	
2)	<i>Kaoru Kawabata</i> Kaoru KAWABATA	5/15/2017
3)	Ryousuke NAKAMURA	
4)	Hiroshige KIKUCHI	
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2) _____ Kaoru KAWABATA _____	_____
3) <u>Ryousuke NAKAMURA</u> Ryousuke NAKAMURA _____	<u>4/25/2019</u> _____
4) _____ Hiroshige KIKUCHI _____	_____
5) _____ Susumu IKEDA _____	_____
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3) ..... Ryouzuke NAKAMURA	.....
4) <i>Hiroshige Kikuchi</i> ..... Hiroshige KIKUCHI	<i>5/9/2017</i>
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5)	<i>Susumu Ikeda</i> Susumu IKEDA	<i>5/10/2017</i>
6)		
7)		
8)		